

ABSTRACT

Ag ALLOY SPUTTERING TARGET FOR FORMING ELECTROCONDUCTIVE
FILM, AND METHOD OF PRODUCING SAME

The present invention relates to an Ag alloy sputtering target for forming a conductive film, the target comprising: 0.1 to 1.5 mass% in total of one or more of In and Sn which can be solid-solved in Ag, and the balance including Ag and inevitable
5 impurities, wherein the average grain size therein is 1 μm or more and less than 30 μm , the dispersion in the grain size is equal to or less than 30% of the average grain size, and the sputtering target is produced by subjecting a melted and cast ingot to hot-rolling, cooling, cold-rolling, heat-treating, and machining in this order.